EA2M

EEPROM Serial 2-Mb SPI

Description

The EA2M is a EEPROM Serial 2−Mb SPI device internally organized as 256Kx8 bits. This features a 256−byte page write buffer and supports the Serial Peripheral Interface (SPI) protocol. The device is enabled through a Chip Select ($\overline{CS}$) input. In addition, the required bus signals are clock input (SCK), data input (SI) and data output (SO) lines. The $\overline{HOLD}$ input may be used to pause any serial communication with the EA2M device. The device features software and hardware write protection, including partial as well as full array protection. On−Chip ECC (Error Correction Code) makes the device suitable for high reliability applications.

The EA2M device is designed for ultra−low power consumption, targeting real−time data logging applications, hearing aids and other medical devices and battery operated applications.

Features

- 5 MHz SPI Compatible
- Supply Voltage Range: 1.6 V to 3.6 V
- SPI Modes (0,0) & (1,1)
- 256−byte Page Write Buffer
- Additional Identification Page with Permanent Write Protection
- Self−timed Write Cycle
- Hardware and Software Protection
- Block Write Protection – Protect 1/4, 1/2 or Entire EEPROM Array
- Low Power CMOS Technology
- 1,000,000 Program/Erase Cycles
- 100 Year Data Retention
- WLCSP 8−ball Package, and Die Sales
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

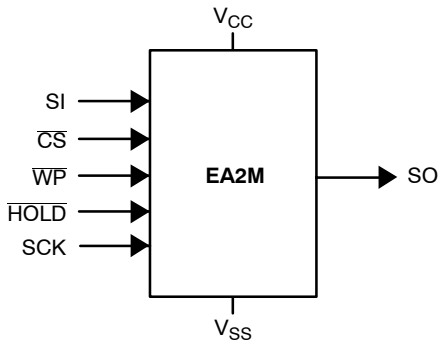

Figure 1. Functional Symbol

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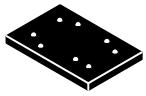
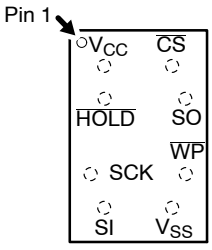


WLCSP8
CASE 567GV

PIN CONFIGURATION



WLCSP8 (Top View)

PIN FUNCTION

Pin Name	Function
$\overline{CS}$	Chip Select
SO	Serial Data Output
$\overline{WP}$	Write Protect
V_{SS}	Ground
SI	Serial Data Input
SCK	Serial Clock
$\overline{HOLD}$	Hold Transmission Input
V_{CC}	Power Supply

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 14 of this data sheet.

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MARKING DIAGRAM

(WLCSP8)

EA2M = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

Table 1. ABSOLUTE MAXIMUM RATINGS

Parameters	Ratings	Units
Operating Temperature	0 to +85	°C
Storage Temperature	−10 to +90	°C
Voltage on any Pin with Respect to Ground (Note 1)	−0.5 to +6.5	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The DC input voltage on any pin should not be lower than −0.5 V or higher than V_{CC} + 0.5 V. During transitions, the voltage on any pin may undershoot to no less than −1.5 V or overshoot to no more than V_{CC} + 1.5 V, for periods of less than 20 ns.

Table 2. RELIABILITY CHARACTERISTICS (Note 5)

Symbol	Parameter	Min	Units
N_{END} (Notes 2, 3)	Endurance	1,000,000	Program/Erase Cycles
T_{DR}	Data Retention	100	Years

2. Page Mode, V_{CC} = 5 V, 25°C.
3. The device uses ECC (Error Correction Code) logic with 6 ECC bits to correct one bit error in 4 data bytes. Therefore, when a single byte has to be written, 4 bytes (including the ECC bits) are re−programmed. It is recommended to write by multiple of 4 bytes located at addresses 4N, 4(N+1), 4(N+2), 4(N+3), in order to benefit from the maximum number of write cycles.

Table 3. D.C. OPERATING CHARACTERISTICS (V_{CC} = 1.6 V to 3.6 V, T_A = 0°C to +70°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions	Min	Max	Units
I_{CCR}	Supply Current (Read Mode)	V_{CC} = 3.6 V, SO open, f_{CLK} = 5 MHz		0.8	mA
		V_{CC} = 1.6 V, SO open, f_{CLK} = 5 MHz		0.4	
I_{CCW}	Supply Current (Write Mode)	V_{CC} = 3.6 V		1.0	mA
		V_{CC} = 1.6 V		0.7	
I_{SB1} (Note 4)	Standby Current	V_{IN} = GND or V_{CC}, CS = V_{CC}, WP = V_{CC}, HOLD = V_{CC}		1	μA
I_{SB2} (Note 4)	Standby Current	V_{IN} = GND or V_{CC}, CS = V_{CC}, WP = GND, HOLD = GND		3	μA
I_L	Input Leakage Current	V_{IN} = GND or V_{CC}	−1	1	μA
I_{LO}	Output Leakage Current	CS = V_{CC}, V_{OUT} = GND or V_{CC}	−1	1	μA
V_{IL1}	Input Low Voltage	$V_{CC} \geq$ 2.5 V	−0.5	0.3 x V_{CC}	V
V_{IH1}	Input High Voltage	$V_{CC} \geq$ 2.5 V	0.7 x V_{CC}	V_{CC} + 0.5	V
V_{IL1}	Input Low Voltage	V_{CC} < 2.5 V	−0.5	0.25 x V_{CC}	V
V_{IH1}	Input High Voltage	V_{CC} < 2.5 V	0.75 x V_{CC}	V_{CC} + 0.5	V
V_{OL1}	Output Low Voltage	$V_{CC} \geq$ 2.5 V, I_{OL} = 3.0 mA		0.4	V
V_{OH1}	Output High Voltage	$V_{CC} \geq$ 2.5 V, I_{OH} = −1.6 mA	V_{CC} − 0.8		V
V_{OL2}	Output Low Voltage	V_{CC} < 2.5 V, I_{OL} = 150 μA		0.2	V
V_{OH2}	Output High Voltage	V_{CC} < 2.5 V, I_{OH} = −100 μA	V_{CC} − 0.2		V

4. When not driven, the WP and HOLD inputs are pulled up to V_{CC} internally. For noisy environments, when the pin is not used, it is recommended the WP and HOLD input to be tied to V_{CC}, either directly or through a resistor.

Table 4. PIN CAPACITANCE (Note 5) (T_A = 25°C, f = 1.0 MHz, V_{CC} = +5.0 V)

Symbol	Test	Conditions	Min	Typ	Max	Units
C_{OUT}	Output Capacitance (SO)	V_{OUT} = 0 V			8	pF
C_{IN}	Input Capacitance ($\overline{CS}$, SCK, SI, $\overline{WP}$, $\overline{HOLD}$)	V_{IN} = 0 V			8	pF

5. These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC−Q100 and JEDEC test methods.

Table 5. A.C. CHARACTERISTICS (V_{CC} = 1.6 V to 3.6 V, T_A = 0°C to +70°C, unless otherwise specified.) (Note 6)

Symbol	Parameter	Min	Max	Units
f_{SCK}	Clock Frequency	DC	5	MHz
t_{SU}	Data Setup Time	20		ns
t_H	Data Hold Time	20		ns
t_{WH}	SCK High Time	75		ns
t_{WL}	SCK Low Time	75		ns
t_{LZ}	$\overline{HOLD}$ to Output Low Z		50	ns
t_{RI} (Note 7)	Input Rise Time		2	μs
t_{FI} (Note 7)	Input Fall Time		2	μs
t_{HD}	$\overline{HOLD}$ Setup Time	0		ns
t_{CD}	$\overline{HOLD}$ Hold Time	10		ns
t_V	Output Valid from Clock Low		75	ns
t_{HO}	Output Hold Time	0		ns
t_{DIS}	Output Disable Time		50	ns
t_{HZ}	$\overline{HOLD}$ to Output High Z		100	ns
t_{CS}	$\overline{CS}$ High Time	80		ns
t_{CSS}	$\overline{CS}$ Setup Time	60		ns
t_{CSH}	$\overline{CS}$ Hold Time	60		ns
t_{CNS}	$\overline{CS}$ Inactive Setup Time	60		ns
t_{CNH}	$\overline{CS}$ Inactive Hold Time	60		ns
t_{WPS}	$\overline{WP}$ Setup Time	20		ns
t_{WPH}	$\overline{WP}$ Hold Time	20		ns
t_{WC} (Note 8, 10)	Write Cycle Time		10	ms

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Table 6. POWER−UP TIMING (Notes 7, 9)

Symbol	Parameter	Min	Max	Units
t_{PUR}, t_{PUW}	Power−up to Read / Write Operation		0.1	ms

6. AC Test Conditions:
   Input Pulse Voltages: 0.3 V_{CC} to 0.7 V_{CC}
   Input rise and fall times: ≤ 10 ns
   Input and output reference voltages: 0.5 V_{CC}
   Output load: current source $I_{OL\ max}/I_{OH\ max}$; C_L = 30 pF
7. This parameter is tested initially and after a design or process change that affects the parameter.
8. t_{WC} is the time from the rising edge of $\overline{CS}$ after a valid write sequence to the end of the internal write cycle.
9. t_{PUR} and t_{PUW} are the delays required from the time V_{CC} is stable until the specified operation can be initiated.
10. The t_{WC} time can be set by the user to allow faster internal writes (max 3 ms) by setting the t_{WC} bit from the Status Register. The fast write mode is recommended for V_{CC} > 2.5 V.

Pin Description

SI: The serial data input pin accepts op−codes, addresses and data. In SPI modes (0,0) and (1,1) input data is latched on the rising edge of the SCK clock input.

SO: The serial data output pin is used to transfer data out of the device. In SPI modes (0,0) and (1,1) data is shifted out on the falling edge of the SCK clock.

SCK: The serial clock input pin accepts the clock provided by the host and used for synchronizing communication between host and EA2M.

$\overline{\text{CS}}$: The chip select input pin is used to enable/disable the EA2M. When $\overline{\text{CS}}$ is high, the SO output is tri−stated (high impedance) and the device is in Standby Mode (unless an internal write operation is in progress). *Every communication session between host and EA2M must be preceded by a high to low transition and concluded with a low to high transition of the $\overline{\text{CS}}$ input.*

$\overline{\text{WP}}$: The write protect input pin will allow all write operations to the device when held high. When $\overline{\text{WP}}$ pin is tied low and the WPEN bit in the Status Register (refer to Status Register description, later in this Data Sheet) is set to "1", writing to the Status Register is disabled.

$\overline{\text{HOLD}}$: The $\overline{\text{HOLD}}$ input pin is used to pause transmission between host and EA2M, without having to retransmit the entire sequence at a later time. To pause, $\overline{\text{HOLD}}$ must be taken low and to resume it must be taken back high, with the SCK input low during both transitions.

Functional Description

The EA2M device supports the Serial Peripheral Interface (SPI) bus protocol, modes (0,0) and (1,1). The device contains an 8−bit instruction register. The instruction set and associated op−codes are listed in Table 7.

Reading data stored in the EA2M is accomplished by simply providing the READ command and an address. Writing to the EA2M, in addition to a WRITE command, address and data, also requires enabling the device for writing by first setting certain bits in a Status Register, as will be explained later.

After a high to low transition on the $\overline{\text{CS}}$ input pin, the EA2M will accept any one of the six instruction op−codes listed in Table 7 and will ignore all other possible 8−bit combinations. The communication protocol follows the timing from Figure 2.

The EA2M features an additional Identification Page (256 bytes) which can be accessed for Read and Write operations when the IPL bit from the Status Register is set to "1". The user can also choose to make the Identification Page permanent write protected by setting the LIP bit from the Status Register (LIP="1").

Table 7. INSTRUCTION SET

Instruction	Opcode	Operation
WREN	0000 0110	Enable Write Operations
WRDI	0000 0100	Disable Write Operations
RDSR	0000 0101	Read Status Register
WRSR	0000 0001	Write Status Register
READ	0000 0011	Read Data from Memory
WRITE	0000 0010	Write Data to Memory

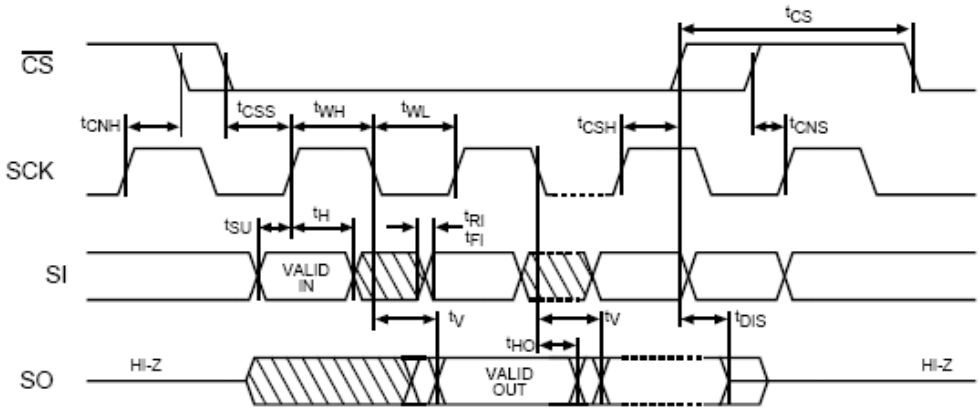


Figure 2. Synchronous Data Timing

Status Register

The Status Register, as shown in Table 8, contains a number of status and control bits.

The $\overline{\text{RDY}}$ (Ready) bit indicates whether the device is busy with a write operation. This bit is automatically set to 1 during an internal write cycle, and reset to 0 when the device is ready to accept commands. For the host, this bit is read only.

The WEL (Write Enable Latch) bit is set/reset by the WREN/WRDI commands. When set to 1, the device is in a Write Enable state and when set to 0, the device is in a Write Disable state.

The BP0 and BP1 (Block Protect) bits determine which blocks are currently write protected. They are set by the user with the WRSR command and are non−volatile. The user is allowed to protect a quarter, one half or the entire memory, by setting these bits according to Table 9. The protected blocks then become read−only.

The TWC (Write Cycle Time) bit is set by the user with the WRSR command and is volatile. When set to 0, the device is in a standard write mode with optimum ICC write, when set to 1 the device is in a fast write mode.

Note: The fast write mode is recommended to be used only with VCC > 2.5 V.

The WPEN (Write Protect Enable) bit acts as an enable for the $\overline{\text{WP}}$ pin. Hardware write protection is enabled when the $\overline{\text{WP}}$ pin is low and the WPEN bit is 1. This condition prevents writing to the status register and to the block protected sections of memory. While hardware write protection is active, only the non−block protected memory can be written. Hardware write protection is disabled when the $\overline{\text{WP}}$ pin is high or the WPEN bit is 0. The WPEN bit, $\overline{\text{WP}}$ pin and WEL bit combine to either permit or inhibit Write operations, as detailed in Table 10.

The IPL (Identification Page Latch) bit determines whether the additional Identification Page (IPL = 1) or main memory array (IPL = 0) can be accessed both for Read and Write operations. The IPL bit is set by the user with the WRSR command and is volatile. The IPL bit is automatically reset after read/write operations. The LIP bit is set by the user with the WRSR command and is non-volatile. When set to 1, the Identification Page is permanently write protected (locked in Read-only mode).

Note: The IPL and LIP bits cannot be set to 1 using the same WRSR instruction. If the user attempts to set (“1”) both the IPL and LIP bit in the same time, these bits cannot be written and therefore they will remain unchanged.

Table 8. STATUS REGISTER

7	6	5	4	3	2	1	0
WPEN	IPL	TWC	LIP	BP1	BP0	WEL	$\overline{\text{RDY}}$

Table 9. BLOCK PROTECTION BITS

Status Register Bits		Array Address Protected	Protection
BP1	BP0		
0	0	None	No Protection
0	1	30000h−3FFFFh	Quarter Array Protection
1	0	20000h−3FFFFh	Half Array Protection
1	1	00000h−3FFFFh	Full Array Protection

Table 10. WRITE PROTECT CONDITIONS

WPEN	$\overline{\text{WP}}$	WEL	Protected Blocks	Unprotected Blocks	Status Register
0	X	0	Protected	Protected	Protected
0	X	1	Protected	Writable	Writable
1	Low	0	Protected	Protected	Protected
1	Low	1	Protected	Writable	Protected
X	High	0	Protected	Protected	Protected
X	High	1	Protected	Writable	Writable

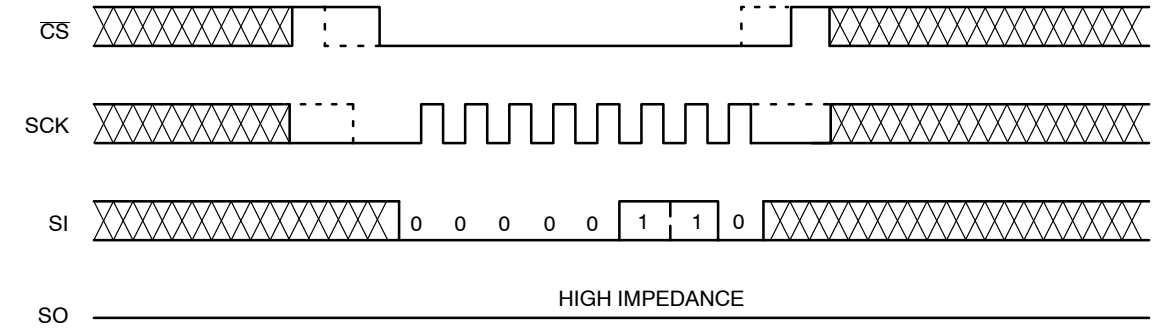
Write Operations

The EA2M device powers up into a write disable state. The device contains a Write Enable Latch (WEL) which must be set before attempting to write to the memory array or to the status register. In addition, the address of the memory location(s) to be written must be outside the protected area, as defined by BP0 and BP1 bits from the status register.

Write Enable and Write Disable

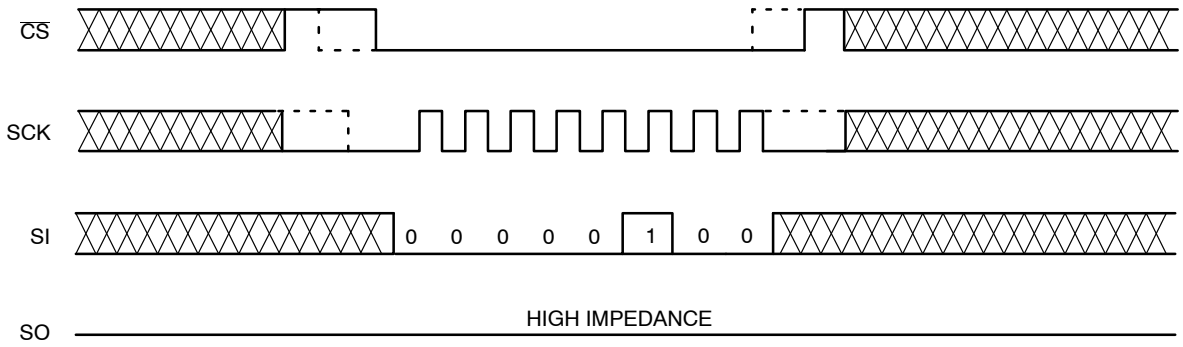
The internal Write Enable Latch and the corresponding Status Register WEL bit are set by sending the WREN instruction to the EA2M. Care must be taken to take the $\overline{CS}$ input high after the WREN instruction, as otherwise the Write Enable Latch will not be properly set. WREN timing is illustrated in Figure 3. The WREN instruction must be sent prior any WRITE or WRSR instruction.

The internal write enable latch is reset by sending the WRDI instruction as shown in Figure 4. Disabling write operations by resetting the WEL bit, will protect the device against inadvertent writes.



Note: Dashed Line = mode (1, 1) - - - - - - - - - - - -

Figure 3. WREN Timing



Note: Dashed Line = mode (1, 1) - - - - - - - - - - - -

Figure 4. WRDI Timing

Byte Write

Once the WEL bit is set, the user may execute a write sequence, by sending a WRITE instruction, a 24−bit address and a data byte as shown in Figure 5. Only 18 significant address bits are used by the EA2M. The rest are don't care bits, as shown in Table 11. Internal programming will start after the low to high $\overline{CS}$ transition. During an internal write cycle, all commands, except for RDSR (Read Status Register) will be ignored. The $\overline{RDY}$ bit will indicate if the internal write cycle is in progress ($\overline{RDY}$ high), or the device is ready to accept commands ($\overline{RDY}$ low).

Page Write

After sending the first data byte to the EA2M, the host may continue sending data, up to a total of 256 bytes, according to timing shown in Figure 6. After each data byte, the lower order address bits are automatically incremented, while the higher order address bits (page address) remain unchanged. If during this process the end of page is exceeded, then loading will "roll over" to the first byte in the page, thus possibly overwriting previouly loaded data. Following completion of the write cycle, the EA2M is automatically returned to the write disable state.

Write Identification Page

The additional 256-byte Identification Page (IP) can be written with user data using the same Write commands sequence as used for Page Write to the main memory array (Figure 6). ***The IPL bit from the Status Register must be set (IPL = 1) using the WRSR instruction, before attempting to write to the IP. Prior to any write to the Identification Page, the Write Enable Latch must be set (WEL=1) by sending the WREN instruction.***

The address bits [A23:A8] are Don't Care and the [A7:A0] bits define the byte address within the Identification Page. In addition, the Byte Address must point to a location outside the protected area defined by the BP1, BP0 bits from the Status Register. When the full memory array is write protected (BP1, BP0 = 1,1), the write instruction to the IP is not accepted and not executed.

Also, the write to the IP is not accepted if the LIP bit from the Status Register is set to 1 (the page is locked in Read-only mode).

Table 11. BYTE ADDRESS

Device	Address Significant Bits	Address Don't Care Bits	# Address Clock Pulses
Main Memory Array	A17 – A0	A23 – A18	24
Identification Page	A7 – A0	A23 – A8	24

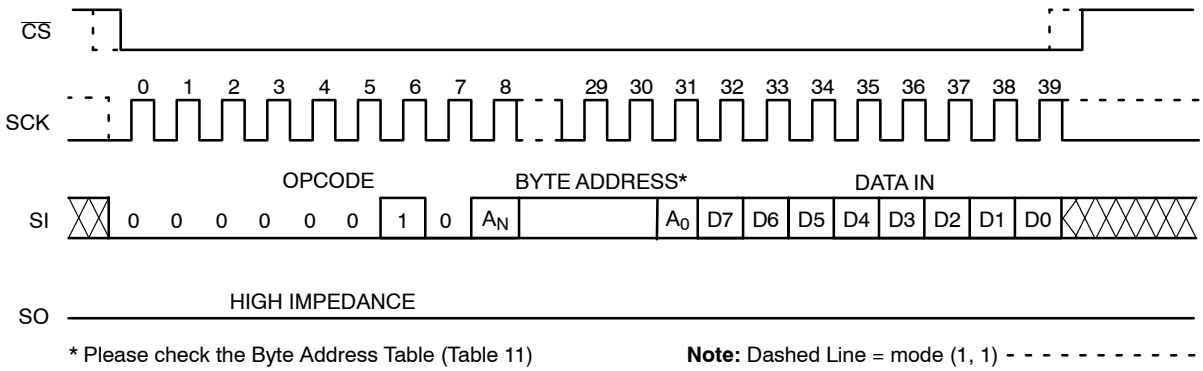


Figure 5. Byte WRITE Timing

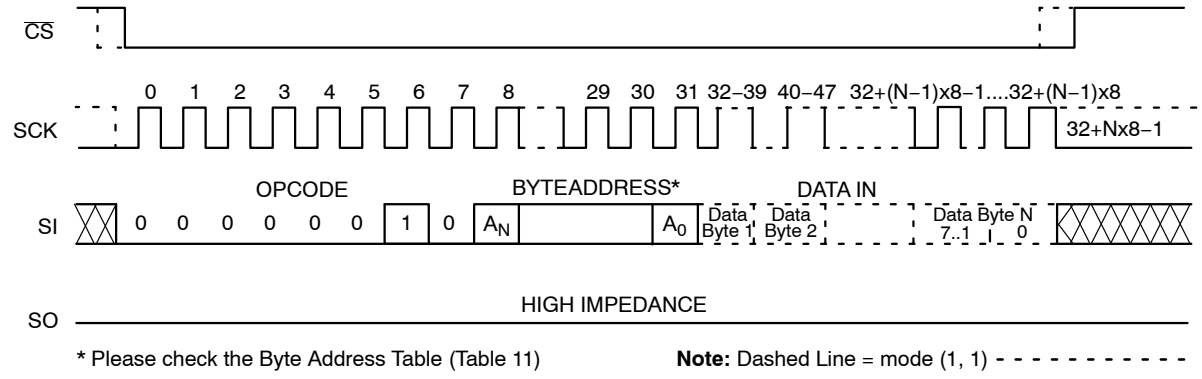


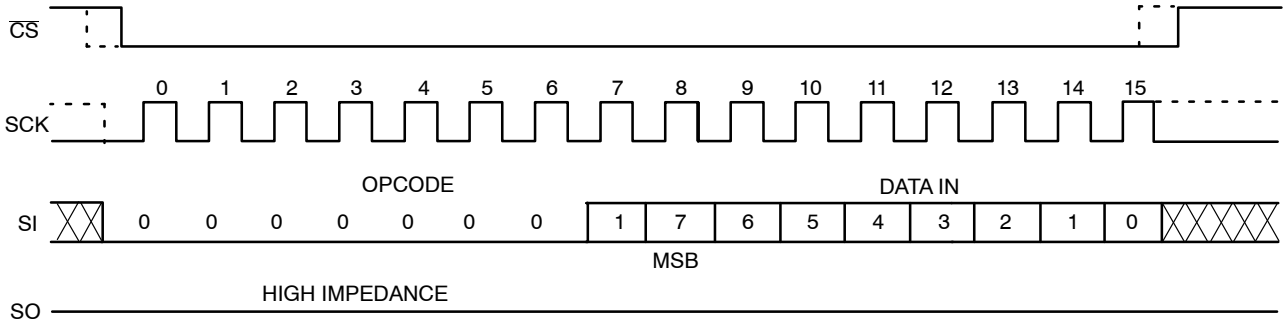
Figure 6. Page WRITE Timing

Write Status Register

The Status Register is written by sending a WRSR instruction according to timing shown in Figure 7. Only bits 2, 3, 4, 5, 6 and 7 can be written using the WRSR command.

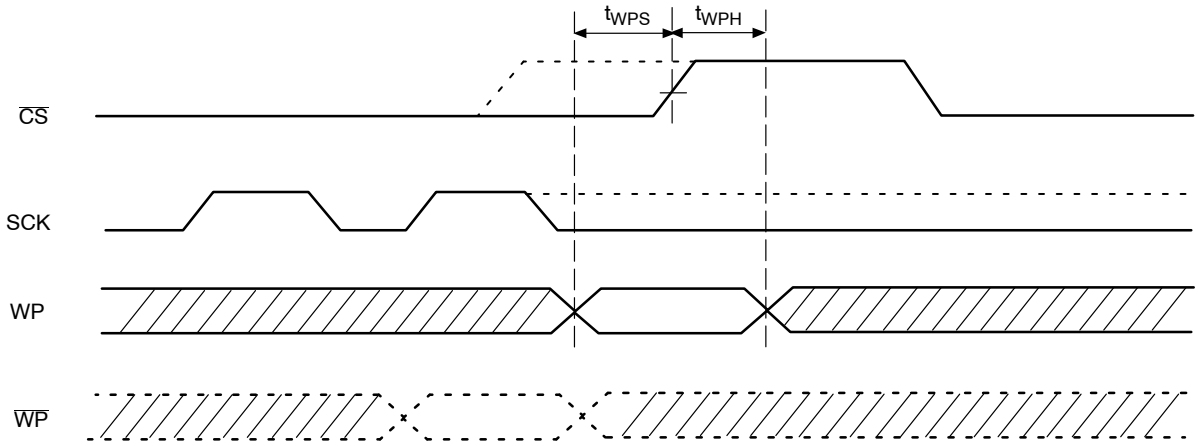
Write Protection

The Write Protect ($\overline{WP}$) pin can be used to protect the Block Protect bits BP0 and BP1 against being inadvertently altered. When $\overline{WP}$ is low and the WPEN bit is set to “1”, write operations to the Status Register are inhibited. $\overline{WP}$ going low while $\overline{CS}$ is still low will interrupt a write to the status register. If the internal write cycle has already been initiated, $\overline{WP}$ going low will have no effect on any write operation to the Status Register. The $\overline{WP}$ pin function is blocked when the WPEN bit is set to “0”. The $\overline{WP}$ input timing is shown in Figure 8.



Note: Dashed Line = mode (1, 1) - - - - - - - - - - - -

Figure 7. WRSR Timing



Note: Dashed Line = mode (1, 1) - - - - - - - - - - - -

Figure 8. $\overline{WP}$ Timing

Read Operations

Read from Memory Array

To read from memory, the host sends a READ instruction followed by a 24−bit address (see Table 11 for the number of significant address bits).

After receiving the last address bit, the EA2M will respond by shifting out data on the SO pin (as shown in Figure 9). Sequentially stored data can be read out by simply continuing to run the clock. The internal address pointer is automatically incremented to the next higher address as data is shifted out. After reaching the highest memory address, the address counter "rolls over" to the lowest memory address, and the read cycle can be continued indefinitely. The read operation is terminated by taking $\overline{CS}$ high.

Read Identification Page

Reading the additional 256-byte Identification Page (IP) is achieved using the same Read command sequence as used for Read from main memory array (Figure 10). ***The IPL bit from the Status Register must be set (IPL = 1) before attempting to read from the IP.*** The [A7:A0] are the address significant bits that point to the data byte shifted out on the SO pin. If the CS continues to be held low, the internal address register defined by [A7:A0] bits is automatically incremented and the next data byte from the IP is shifted out. The byte address must not exceed the 256-byte page boundary.

Read Status Register

To read the status register, the host simply sends a RDSR command. After receiving the last bit of the command, the EA2M will shift out the contents of the status register on the SO pin (Figure 10). The status register may be read at any time, including during an internal write cycle.

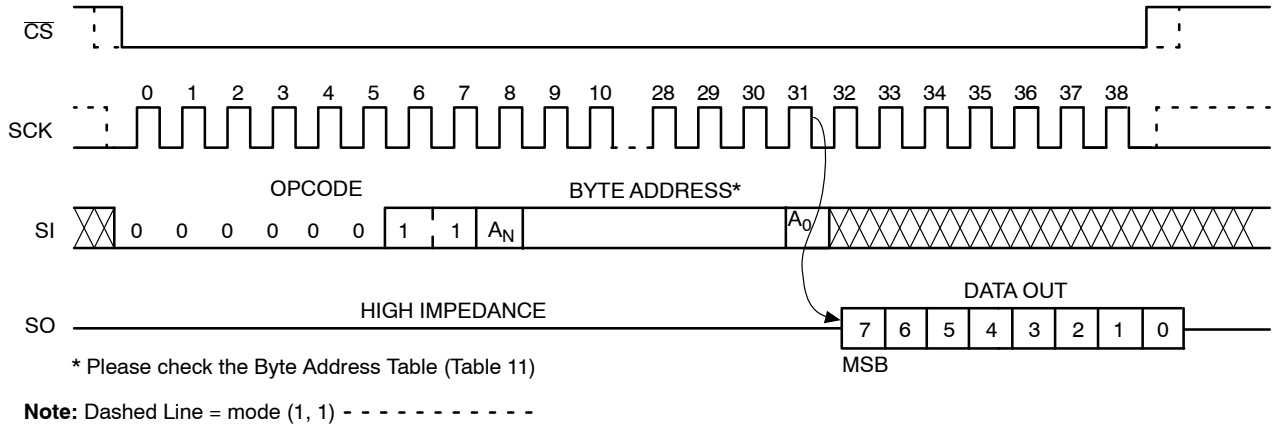


Figure 9. READ Timing

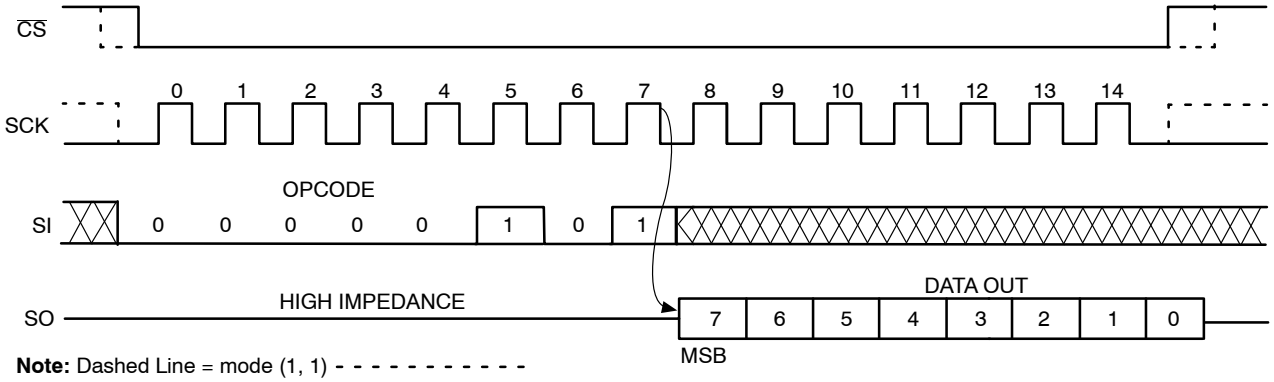


Figure 10. RDSR Timing

Hold Operation

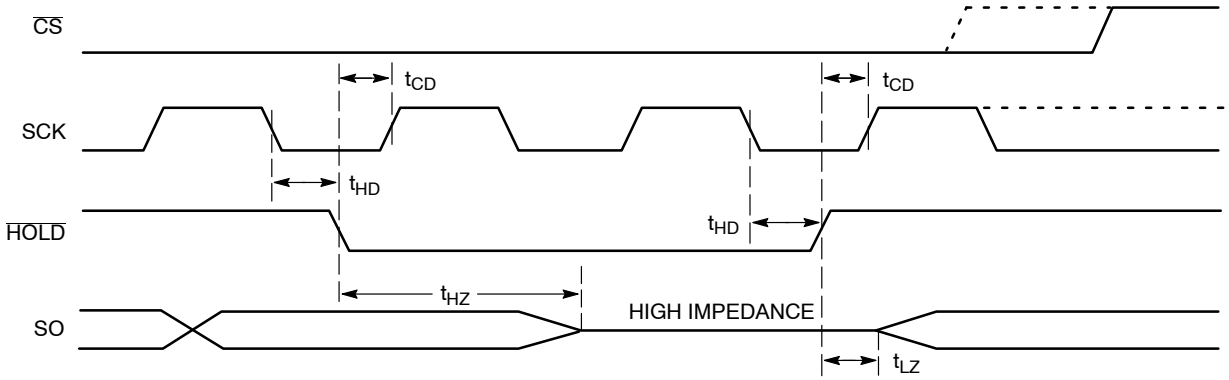
The $\overline{\text{HOLD}}$ input can be used to pause communication between host and EA2M. To pause, $\overline{\text{HOLD}}$ must be taken low while SCK is low (Figure 11). During the hold condition the device must remain selected ($\overline{\text{CS}}$ low). During the pause, the data output pin (SO) is tri−stated (high impedance) and SI transitions are ignored. To resume communication, $\overline{\text{HOLD}}$ must be taken high while SCK is low.

Design Considerations

The EA2M device incorporates Power−On Reset (POR) circuitry which protects the internal logic against powering up in the wrong state. The device will power up into Standby mode after V_{CC} exceeds the POR trigger level and will power down into Reset mode when V_{CC} drops below the POR trigger level. This bi−directional POR behavior protects the device against ‘brown−out’ failure following a temporary loss of power.

The EA2M device powers up in a write disable state and in a low power standby mode. A WREN instruction must be issued prior any writes to the device.

After power up, the CS pin must be brought low to enter a ready state and receive an instruction. After a successful byte/page write or status register write, the device goes into a write disable mode. The CS input must be set high after the proper number of clock cycles to start the internal write cycle. Access to the memory array during an internal write cycle is ignored and programming is continued. Any invalid op−code will be ignored and the serial output pin (SO) will remain in the high impedance state.

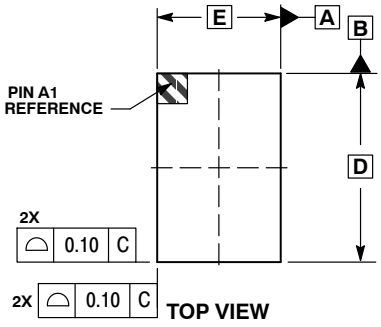


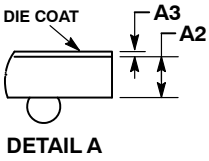
Note: Dashed Line = mode (1, 1) - - - - - - - - - - -

Figure 11. $\overline{\text{HOLD}}$ Timing

PACKAGE DIMENSIONS

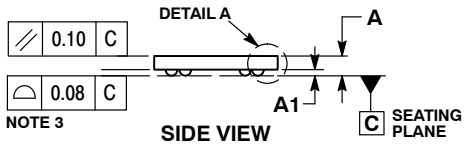
WLCSP8, 3.12x2.04
CASE 567GV
ISSUE B

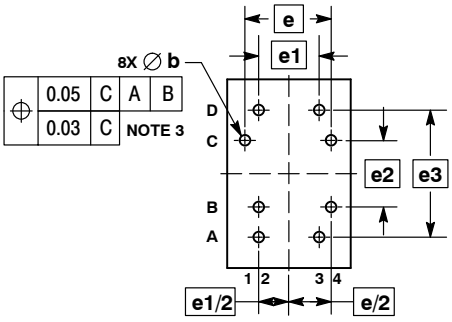




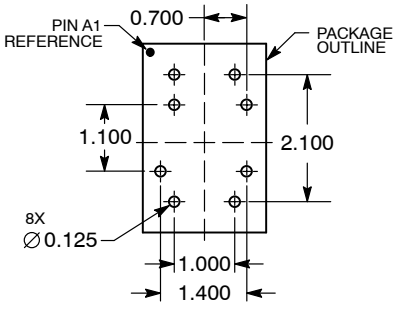
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DIMENSION b IS MEASURED AT THE MAXIMUM BALL DIAMETER PARALLEL TO DATUM C.

	MILLIMETERS	
DIM	MIN	MAX
A	---	0.37
A1	0.06	0.10
A2	0.23 REF	
A3	0.025 REF	
b	0.11	0.14
D	3.12 BSC	
E	2.04 BSC	
e	1.40 BSC	
e1	1.00 BSC	
e2	1.10 BSC	
e3	2.10 BSC	





RECOMMENDED SOLDERING FOOTPRINT*



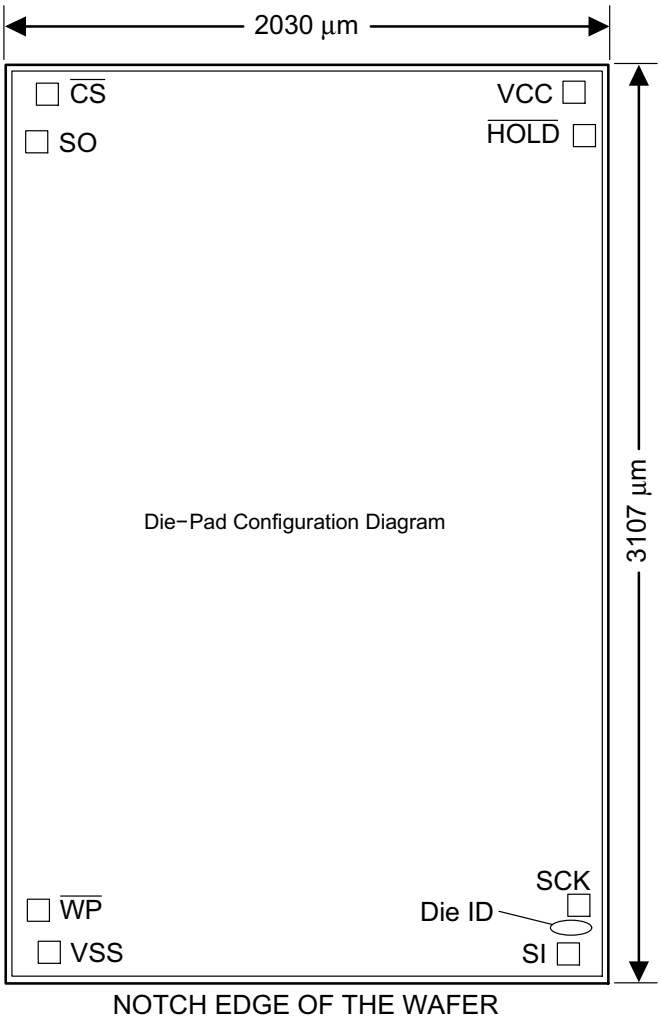
DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PIN NUMBERING

Pin Index	Pin Functionality
A2	V_{CC}
A3	$\overline{CS}$
B2	$\overline{HOLD}$
B4	SO
C1	SCK
C4	$\overline{WP}$
D2	SI
D3	V_{SS}

DIE SIZE AND PAD LOCATION



Pad Location*

Pad	Pad Name	X	Y	Unit
1	$\overline{CS}$	-878.14	1482.5	μm
2	SO	-918.14	1314.5	μm
3	$\overline{WP}$	-918.14	-1342.5	μm
4	GND	-878.14	-1482.5	μm
5	SI	888.14	-1467.5	μm
6	SCK	928.14	-1327.5	μm
7	$\overline{HOLD}$	943.14	1342.5	μm
8	VDD	903.14	1482.5	μm

* Pads location coordinates relative to the origin at the center of the die.

Die Mechanical Dimensions

Specification	Min	Typ	Max	Unit
Bond pad opening	- -	70 x 70 2.755 x 2.755	- -	μm mils
Bond pad spacing	136 5.354	140 5.511	- -	μm mils
Die thickness	- -	203.2 8.0	- -	μm mils
Die size after saw-cut	- -	2030 x 3107 81.889 x 124.291	- -	μm mils

TAPE AND REEL INFORMATION

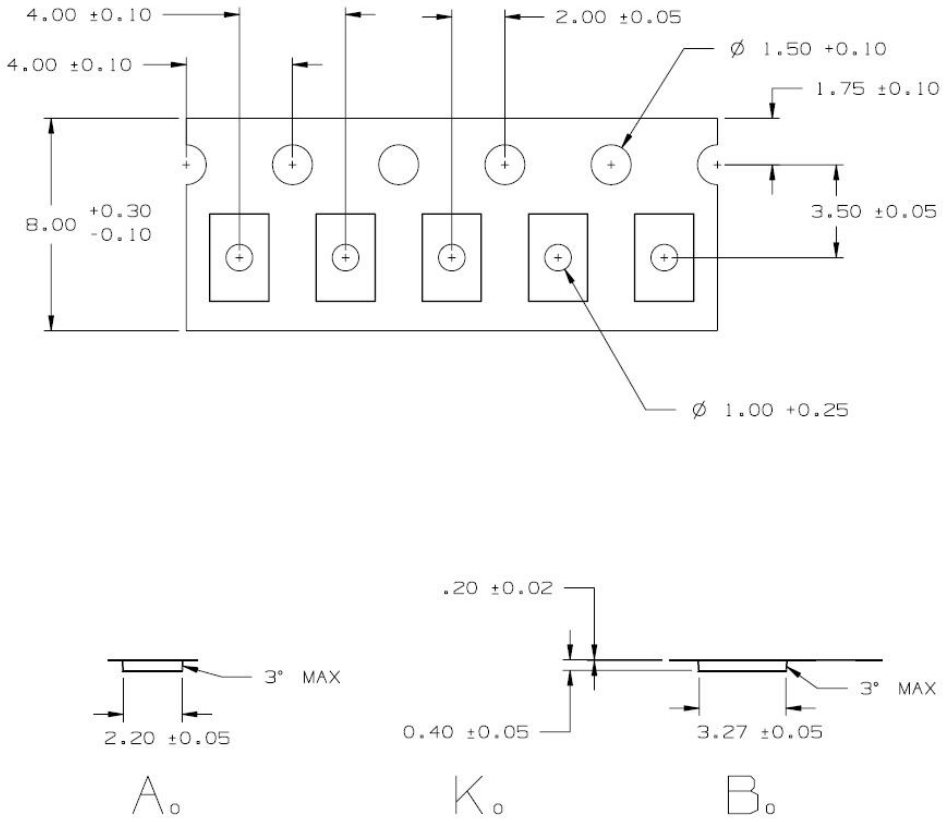


Figure 12. EA2M−SUD Tape & Reel

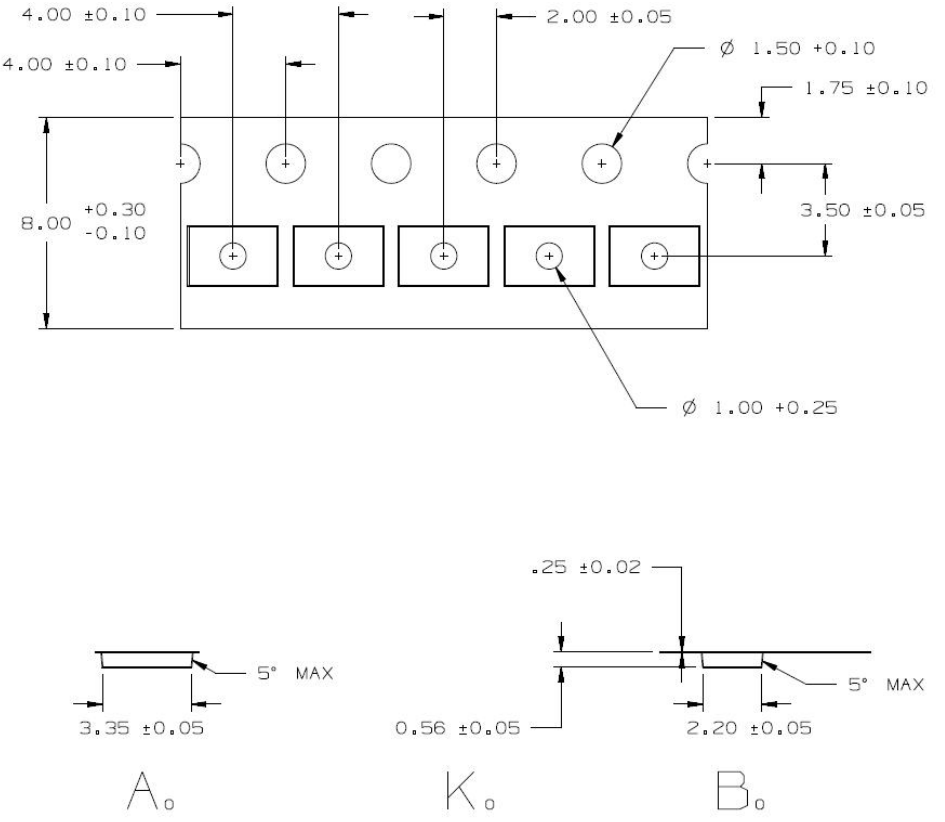


Figure 13. EA2M−SWC Tape & Reel

ORDERING INFORMATION

Device Order Number	Specific Device Marking	Package Type	Lead Finish	Shipping†
EA2M−SUD8A1G (Notes 12, 14)	−	Die in Tape & Reel		3,000 Units / Tape & Reel
EA2M−SWC8A1G (Notes 13, 14)	EA2M	WLCSP−8 with Die Coat	SnAg	2,000 Units / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

11. All packages are RoHS−compliant (Lead−free, Halogen−free).
12. EA2M−SUD8A1G: Die in Tape & Reel with die thickness = 8 mil ± 0.5 mil. These chips are contained in a Tape and Reel. The mechanical specifications of the trays are shown in Figure 12. Dimensions are in mm.
13. EA2M−SWC8A1G: These chips are contained in a Tape and Reel. The mechanical specifications of the trays are shown in Figure 13. Dimensions are in mm.
14. **Caution:** The EEPROM devices delivered in bare die form or WLCSP must never be exposed to ultra violet light! When exposed to ultra violet light the EEPROM cells lose their stored data.

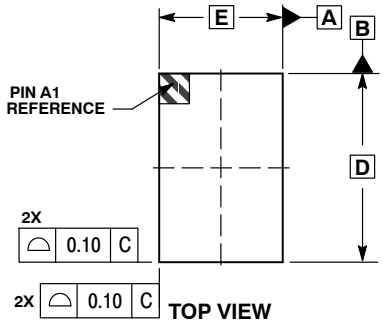
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

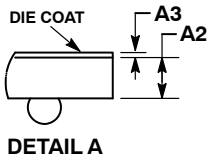
ON Semiconductor®

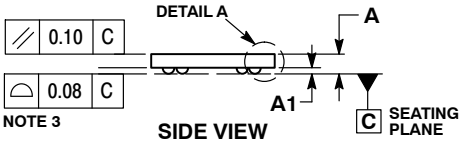
SCALE 4:1

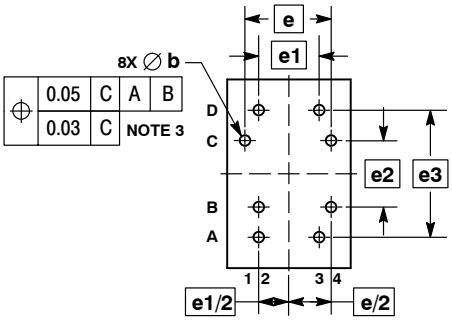
WLCSP8, 3.12x2.04
CASE 567GV
ISSUE B

DATE 17 FEB 2014









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D	3.12 BSC	
E	2.04 BSC	
e	1.40 BSC	
e1	1.00 BSC	
e2	1.10 BSC	
e3	2.10 BSC	

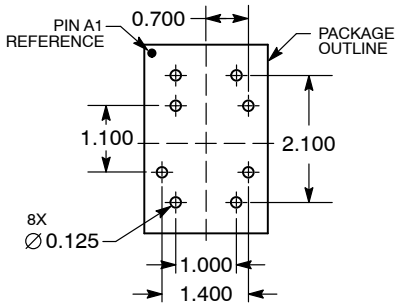
GENERIC MARKING DIAGRAM*

A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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